



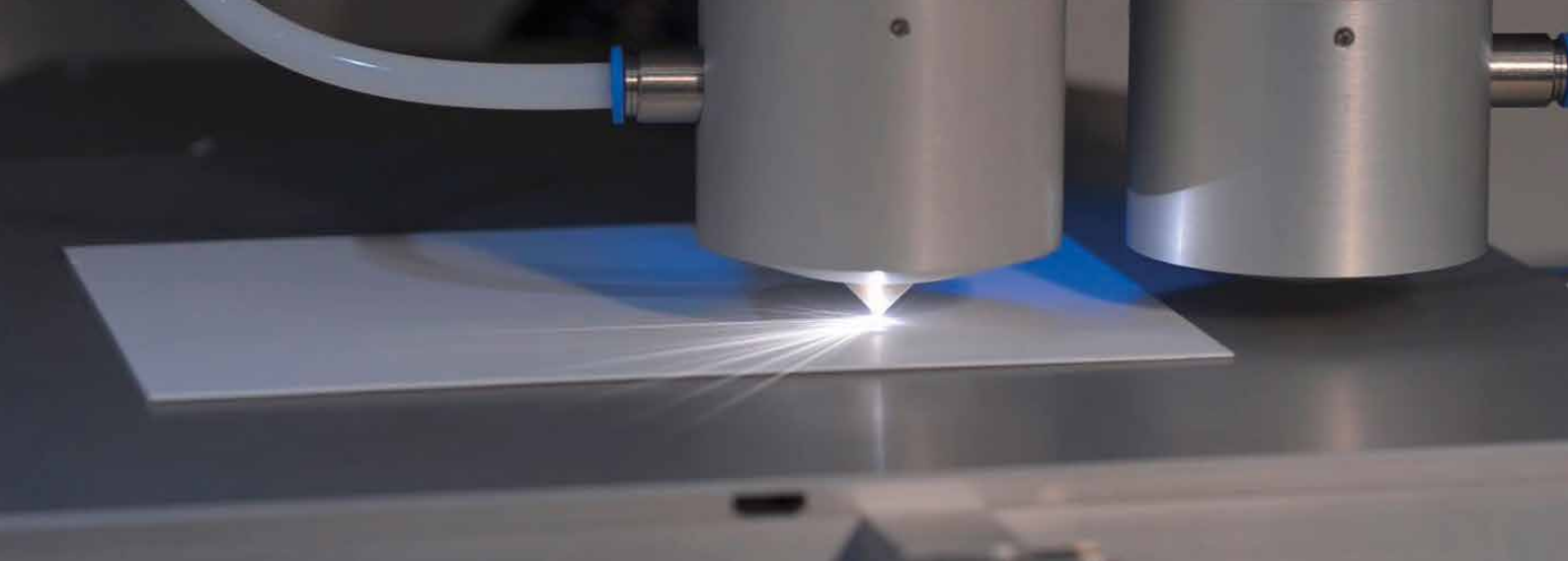
**INNOLAS**  
solutions

INNOVATION FOR THE  
NEXT GENERATION



# **ILS-LT** *LINEAR TABLE MACHINE*

**VERSATILE *LASER SYSTEM***  
**FOR MICRO MATERIAL PROCESSING**

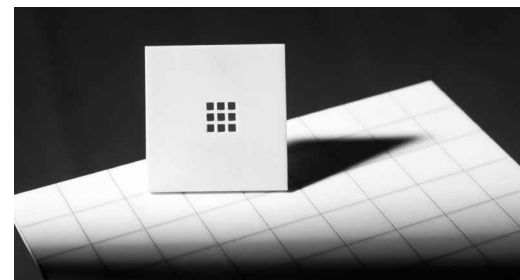
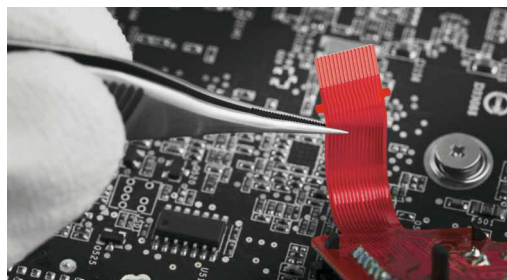


## FEATURES

- ◆ Fixed optic or scanner setup
- ◆ Single or dual process heads
- ◆ Process gas (N<sub>2</sub>, O<sub>2</sub>, Ar, ...)
- ◆ Processing one or more substrates in parallel
- ◆ Automatic camera calibration
- ◆ Automated routines for reference runs
- ◆ Automated process control
- ◆ Automated vision system for precision alignment and scaling, offset, trapezoidal and rotation compensation
- ◆ Stand alone and production line integrated system

## OPTIONS

- ◆ Import of CAD files (e.g. DXF, DWG) and Excellon 2, Sieb & Meyer and Gerber file formats
- ◆ SQL data base for process and event tracking
- ◆ MES interface (SECS GEM PV2)
- ◆ Integrated process metrology
- ◆ Semi-automatic handling (R&D)
- ◆ Fully-automatic handling (production)



## APPLICATIONS

Micro Via Drilling, Routing, Depaneling, Micro Structuring, Selective Ablation, Cavity Formation

## ACCURACY

< +/-10 µm abs.  
< +/-2 µm repeatability

## SUBSTRATE

Dimension up to 610 x 410 mm  
Thickness > 50 µm  
PCB, ceramic, silicon, metal

## AVAILABLE LASER SOURCES

Wave length: 9.4, 10.6 µm (CO<sub>2</sub>), 1064, 1030, 532, 515, 355 nm  
Pulse: µs, ns, ps, fs

## DIMENSIONS

1700 x 2100 x 2700 mm

